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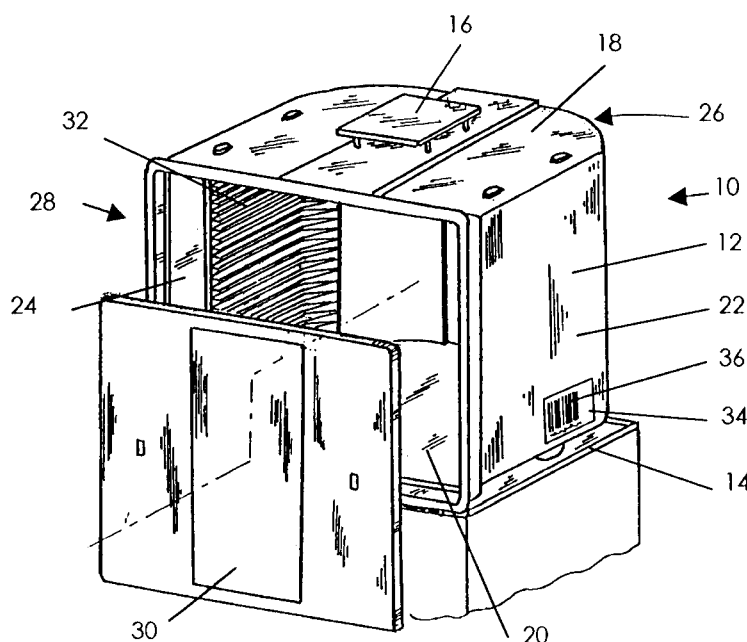
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(54) Title: INFORMATIONAL POLYMER FILM INSERT MOLDING



(57) Abstract: A system and method for using a thin polymer film member (34) to bond indicia (36) in the molding process for manufacturing wafer containers (10) and other plastic articles for use in the semi-conductor manufacturing industry, and particularly such articles for use in semiconductor fabrication clean room environments. The system and method enables multicolored indicia and unique electronically readable indicia to be bonded to the article, while also providing a protective containment barrier to inhibit process contamination stemming from the indicia and to protect the indicia from physical damage.

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